

Amendments to the Claims:

Please amend claim 1 and add claims 46-52 as follows. Following is a complete listing of the claims pending in the application, as amended:

1. (Currently Amended) A microfeature device package system, comprising:
a microfeature device;
a plurality of device contacts electrically coupled to structures within the microfeature device;
a conductive structure electrically connected to at least one of the plurality of device contacts, the conductive structure having a plurality of first and second package contacts accessible for electrical coupling to at least one device external to the package, the first package contacts being accessible from a first direction for coupling and the second package contacts being configured to receive solder balls and being accessible from a second direction for coupling, the second direction being opposite the first direction;
an encapsulant disposed adjacent to the microfeature device and the conductive structure, the encapsulant having apertures with aperture walls aligned with the second package contacts ~~to contain~~ and containing solder balls carried by the second package contacts, the encapsulant being positioned against the conductive structure proximate to the first package contacts; and
individual volumes of solder positioned at individual first ~~and second~~ package contacts.

2. (Original) The system of claim 1 wherein the conductive structure includes a leadframe having a plurality of elongated leadfingers, and wherein the first package contacts includes generally flat, elongated surfaces of the leadfingers, and wherein the second package contacts include end surfaces of the leadfingers.

3. (Original) The system of claim 1 wherein the microfeature device has an at least generally planar first surface facing in the first direction and an at least generally planar second surface facing in the second direction, and wherein the plurality of device contacts are positioned at least proximate to the second surface.

4. (Original) The system of claim 1 wherein the first package contacts are arranged in a first pattern, and wherein the second package contacts are arranged in a second pattern different than the first pattern.

5. (Original) The system of claim 1 wherein the first package contacts are arranged adjacent to a periphery of the package, and wherein the second package contacts are arranged in an array with at least some of the second package contacts spaced apart from the periphery of the package.

6. (Original) The system of claim 1, further comprising solder balls disposed on the second package contacts.

7. (Original) The system of claim 1 wherein the conductive structure includes a leadframe attached to the microfeature device, and wherein the leadframe includes a plurality of elongated leadfingers, with each leadfinger having a first end portion positioned to make electrical contact a first type of external device, each leadfinger further having a second end portion wirebonded to at least one of the device contacts, each leadfinger still further having an intermediate portion between the first and second end portions, the intermediate portion carrying a solder ball to make electrical contact with a second type of external device.

8. (Withdrawn) The system of claim 1 wherein the microfeature device includes a first microfeature device and wherein the device contacts include first device contacts, and wherein the package further comprises a second microfeature device having second device contacts and being stacked relative to the first microfeature device, with the conductive structure being electrically connected to at least one of the second device contacts.

9. (Original) The system of claim 1, further comprising the device external to the package, and wherein the device external to the package includes a printed circuit board having circuitry electrically coupled to of the first package contacts or the second package contacts.

10. (Withdrawn) The system of claim 1, further comprising:
the device external to the package, and wherein the device external to the package
includes a printed circuit board having circuitry electrically coupled to the first
package contacts or the second package contacts;
at least one of a processor and a memory device coupled to the printed circuit board;
an input device coupled to the printed circuit board;
an output device coupled to the printed circuit board; and
an enclosure disposed around the printed circuit board and the microfeature device.

11. (Original) The system of claim 1 wherein the microfeature device includes a
memory chip.

12-45. (Cancelled)

46. (New) A microfeature device package system, comprising:
a microfeature device having a plurality of device contacts;
a conductive structure electrically connected to at least one of the plurality of device
contacts, the conductive structure having a plurality of first package contacts and
second package contacts, individual first and second package contacts having
contact surfaces accessible for electrical coupling to at least one device external to
the package, the first package contacts being accessible from a first direction and
the second package contacts being accessible from a second direction opposite the
first direction; and
an encapsulant disposed adjacent to the microfeature device and the conductive structure,
the encapsulant having apertures aligned with the second package contacts and
having aperture walls extending outwardly from the contact surfaces of the
second package contacts.

47. (New) The system of claim 46 wherein the conductive structure includes a
leadframe having a plurality of elongated leadfingers, and wherein the first package contacts

includes generally flat, elongated surfaces of the leadfingers, and wherein the second package contacts include end surfaces of the leadfingers.

48. (New) The system of claim 46 wherein the first package contacts are arranged in a first pattern, and wherein the second package contacts are arranged in a second pattern different than the first pattern.

49. (New) The system of claim 46, further comprising solder balls disposed in the apertures of the encapsulant and in contact with the contact surfaces of the second package contacts.

50. (New) A microfeature device package system, comprising:
a microfeature device having a plurality of device contacts;
a conductive structure electrically connected to at least one of the plurality of device contacts, the conductive structure having a plurality of first package contacts and second package contacts with individual first and second package contacts having contact surfaces accessible for electrical coupling to at least one device external to the package, the first package contacts being accessible from a first direction and the second package contacts being accessible from a second direction opposite the first direction; and
an encapsulant disposed adjacent to the microfeature device and the conductive structure, and wherein the package system includes a plurality of openings aligned with the second package contacts.

51. (New) The system of claim 50 wherein the conductive structure includes a leadframe having a plurality of elongated leadfingers, and wherein the first package contacts includes generally flat, elongated surfaces of the leadfingers, and wherein the second package contacts include end surfaces of the leadfingers.

51. (New) The system of claim 50 wherein the first package contacts are arranged in a first pattern, and wherein the second package contacts are arranged in a second pattern different than the first pattern.

52. (New) The system of claim 50, further comprising solder balls disposed in the openings and in contact with the second package contacts.